

Appendix – Specification

Marked to Show Changes

CROSS-REFERENCE TO RELATED APPLICATION(S)

[0001] The present application is a continuation-in-part of U.S. Application No. 09/651,797, filed August 30, 2000 and entitled "Methods and Apparatus for Removing Conductive Material from a Microelectronic Substrate;" U.S. Application No. 09/888,084, filed June 21, 2001, and entitled "Methods and Apparatus for Electrical, Mechanical and/or Chemical Removal of Conductive Material from a Microelectronic Substrate;" and U.S. Application No. 09/887,767, filed June 21, 2001, and entitled "Microelectronic Substrate Having Conductive Material With Blunt-Cornered Apparatus, and Associated Methods for Removing Conductive Material;" all of which are herein incorporated in their entirety by reference.

204050-6930001